

Device Features

- OIP3 = 41.0 dBm @ 1900 MHz
- Gain = 15.5 dB @ 1900 MHz
- Output P1 dB = 25.5 dBm @ 1900 MHz
- 50 Ω Cascadable
- RoHS2-compliant SOT-89 SMT package



Product Description

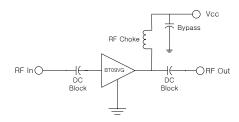
BeRex's BT09VG is a high performance and a high dynamic range amplifier in a low cost surface mount package(SOT-89) with a RoHS2-compliant, that incorporates reliable heterojunction-bipolar-transistor (HBT) devices fabricated with InGaP GaAs technology.

This device is designed for use where high linearity is required and features high OIP3 and P1 with low consumption current (85mA) and requires a few external matching components such as a DC blocking capacitors on the In/Output pin, a bypass capacitor and a RF choke for the out port.

Applications

- Base station Infrastructure/RFID
- Commercial/Industrial/Military wireless system

Application Circuits



^{*}external matching circuit: refer to the page 5 to 14.

Typical Performance¹

Parameter		Unit			
	900	1900	2450	3500	MHz
Gain	21.5	15.5	13.5	10.8	dB
S11	-16.0	-30.0	-14.0	-15.0	dB
S22	-24.0	-19.0	-19.0	-14.0	dB
OIP3 ²	39.0	41.0	41.0	42.0	dBm
P1dB	24.5	25.5	27.0	25.0	dBm
Noise Figure	3.7	4.0	4.7	5.4	dB

 $^{^1\,}$ Device performance $_$ measured on a BeRex evaluation board at 25°C, 50 Ω system.

 $^{^{2}\,}$ OIP3 $_{-}$ measured with two tones at an output of 13 dBm per tone separated by 1 MHz.

	Min.	Typical	Max.	Unit
Bandwidth	5		4000	MHz
I _C @ (Vc = 5V)	140	160	180	mA
V_{C}		5.0		V
R _{TH}		50		°C/W

Absolute Maximum Ratings

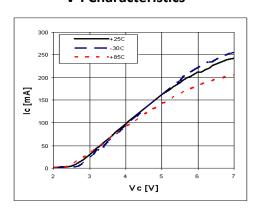
Parameter	Rating	Unit
Operating Case Temperature	-40 to +85	°C
Storage Temperature	-55 to +155	°C
Junction Temperature	+190	°C
Operating Voltage	+7.0	V
Supply Current	220	mA
Input RF Power	23	dBm

 $^{{}^{*}\}text{Operation}$ of this device above any of these parameters may result in permanent damage.

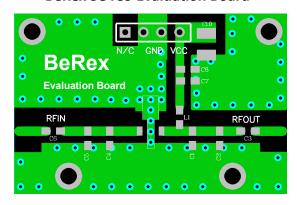




V-I Characteristics



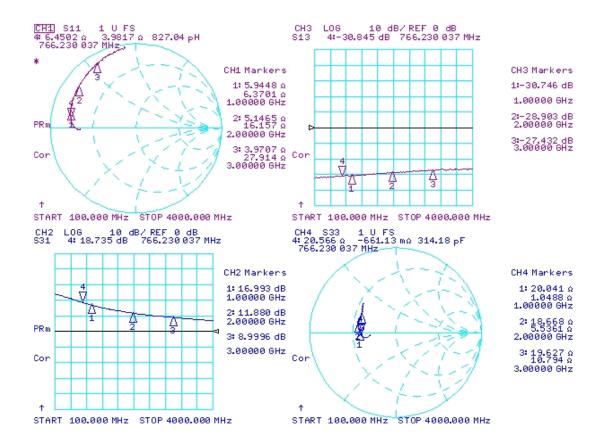
BeRex SOT89 Evaluation Board



*Dielectric constant _ 4.2 *RF pattern width 52mil *31mil thick FR4 PCB

Typical Device Data

S-parameters (Vc=5V, Ic=160mA, T=25°C)



BeRex •website: www.berex.com

•email: <u>sales@berex.com</u>



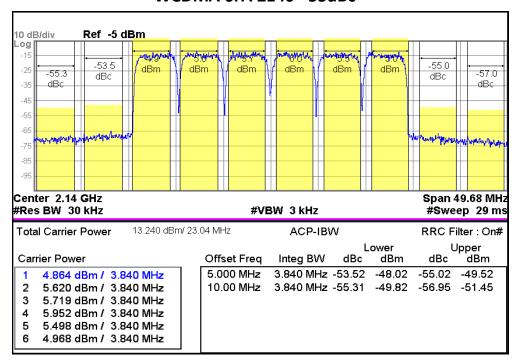
S-Parameter

(Vdevice = 5.0V, Icc = 160mA, T = 25 °C, calibrated to device leads)

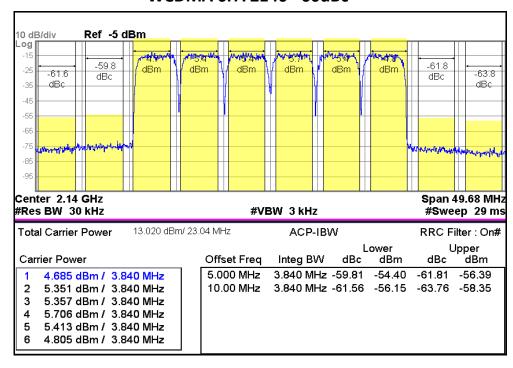
Freq	S11	S11	S21	S21	S12	S12	S22	S22
[MHz]	Mag	Ang	Mag	Ang	Mag	Ang	Mag	Ang
100	0.65	-180.00	16.00	170.00	0.03	2.50	0.30	-170.00
500	0.74	180.00	11.00	130.00	0.03	8.90	0.38	-170.00
1000	0.79	170.00	7.00	98.00	0.03	14.00	0.42	180.00
1500	0.81	150.00	5.00	82.00	0.03	18.00	0.44	170.00
2000	0.83	140.00	3.90	69.00	0.04	19.00	0.46	170.00
2500	0.85	130.00	3.20	57.00	0.04	19.00	0.45	160.00
3000	0.88	120.00	2.80	46.00	0.04	18.00	0.45	150.00
3500	0.92	110.00	2.50	35.00	0.04	14.00	0.48	140.00
4000	0.96	98.00	2.20	23.00	0.05	11.00	0.51	140.00



WCDMA 6FA 2140 -55dBc



WCDMA 6FA 2140 -60dBc



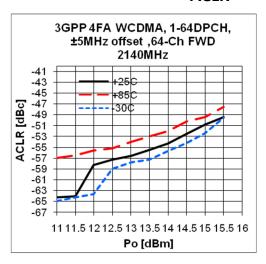
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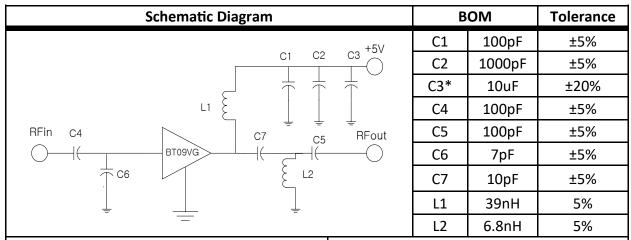
•email: <u>sales@berex.com</u>

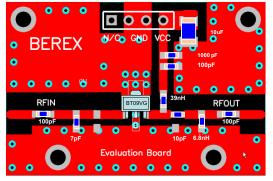


ACLR



Application Circuit: 900 MHz





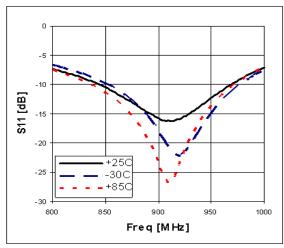
Note:

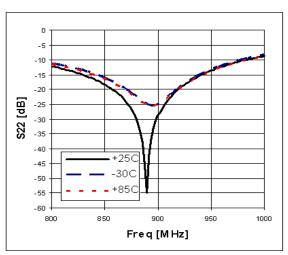
- 1. PCB: 31mil thick FR4.
- 2. Distance between the center of the shunt cap(C6) and the input pin of BT09VG _ **7.0mm**.
- 3. Distance between the center of the series cap(C7) and the output pin of BT09VG _ <u>3.5mm.</u>
- 4. Distance between the center of the shunt inductor(L2) and the output pin of BT09VG _ **5.5mm**.

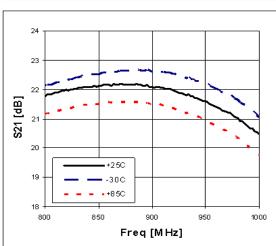


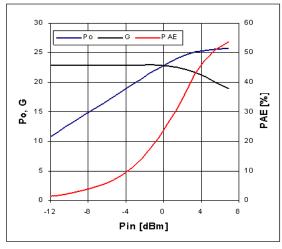


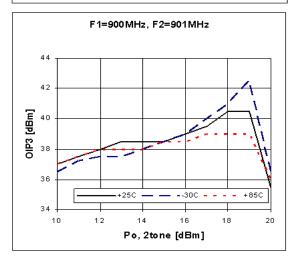
Typical Performance

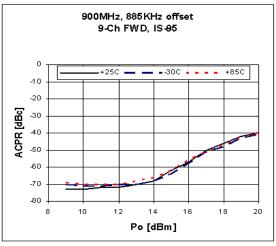












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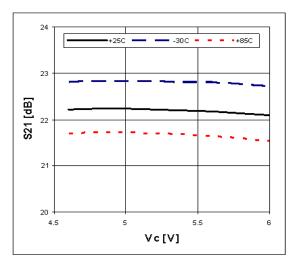
•website: www.berex.com

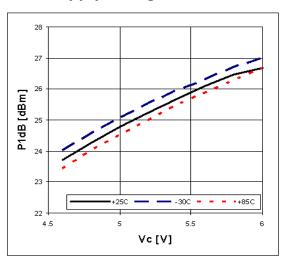
●email: <u>sales@berex.com</u>

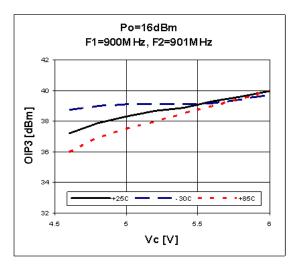


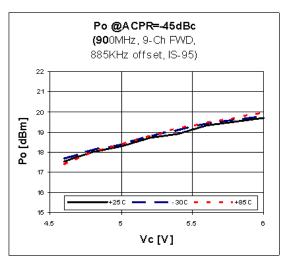


Performance Variation with Supply Voltage





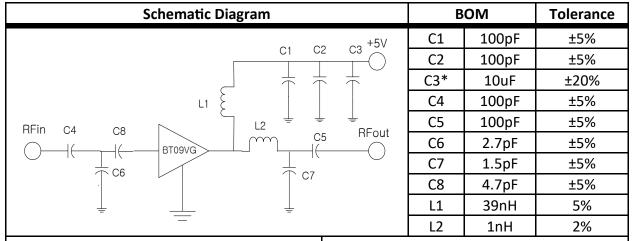


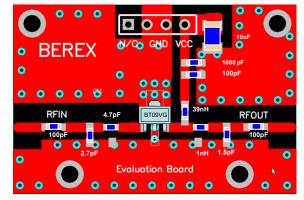






Application Circuit: 1900MHz



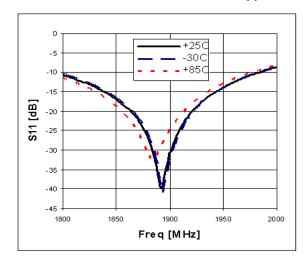


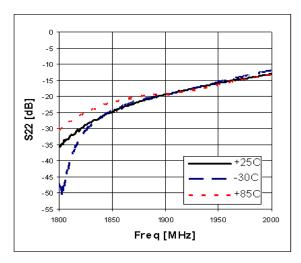
Note: 1. PCB: 31mil thick FR4.

- Distance between the center of the series cap(C8) and the input pin of BT09VG _ 2.5mm.
- 3. Distance between the center of the shunt cap(C6) and the input pin of BT09VG <u>4.0mm</u>.
- 4. Distance between the center of the series inductor (L2) and the output pin of BT09VG **3.5mm.**
- 5. Distance between the center of the shunt cap(C7) and the output pin of BT09VG _ **8.0mm.**

*Skipping C3 reduces device ruggedness.

Typical Performance





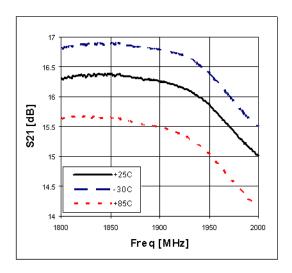
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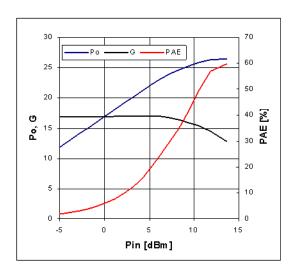
•website: www.berex.com

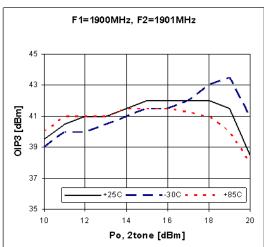
•email: sales@berex.com

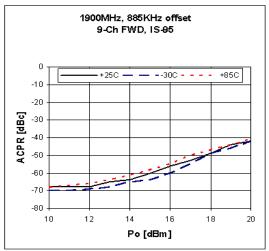








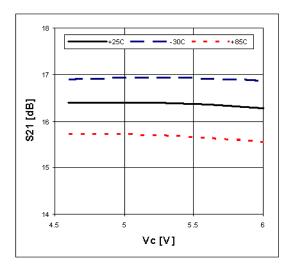


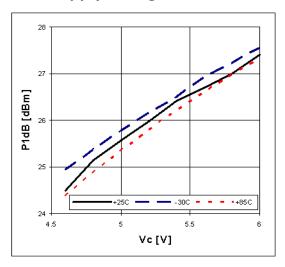


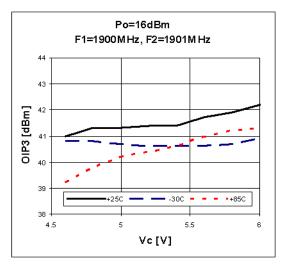


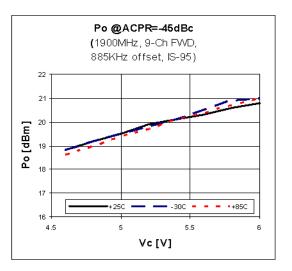


Performance Variation with Supply Voltage





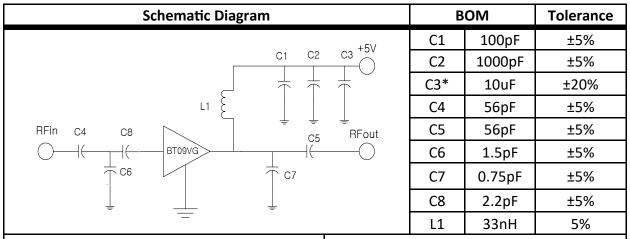


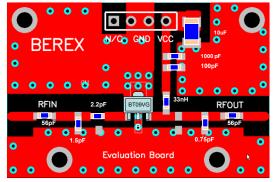






Application Circuit: 2450MHz



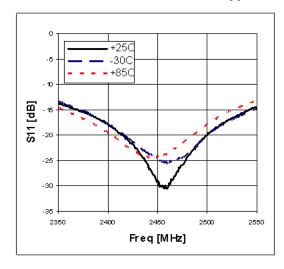


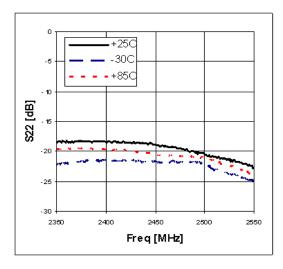
Note:

- 1. PCB: 31mil thick FR4.
- 2. Distance between the center of the series cap(C8) and the input pin of BT09VG _ **2.5mm.**
- Distance between the center of the shunt cap(C6) and the input pin of BT09VG _ 4.0mm.
- 4. Distance between the center of the shunt cap(C7) and the output pin of BT09VG _ 6.2mm.

*Skipping C3 reduces device ruggedness.

Typical Performance





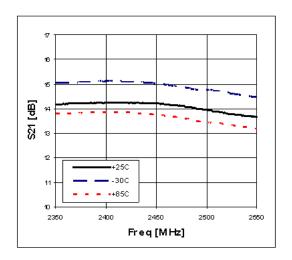
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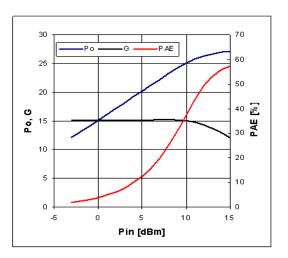
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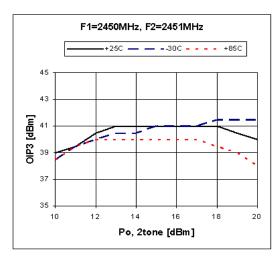
●email: <u>sales@berex.com</u>







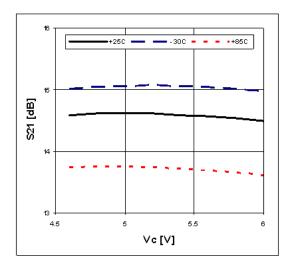


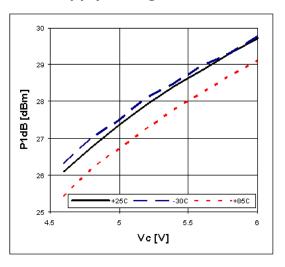


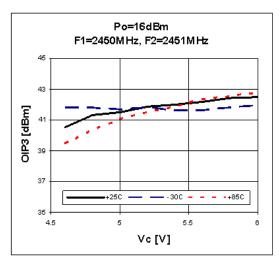


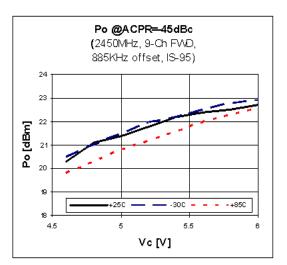


Performance Variation with Supply Voltage





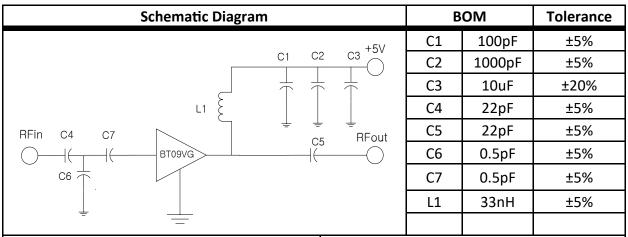


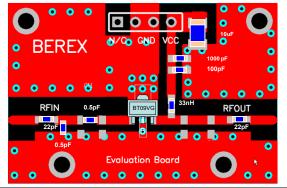






Application Circuit: 3500MHz

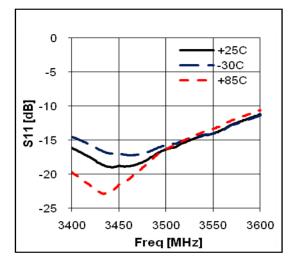


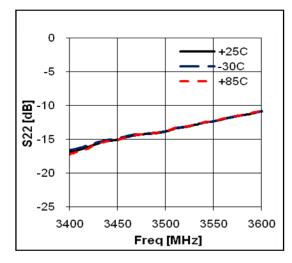


Note:

- 1. PCB: 31mil thick FR4.
- 2. Distance between the center of the series cap(C7) and the input pin of BT09VG _ **2.5**mm.
- 3. Distance between the center of the shunt cap(C6) and the input pin of BT09VG _ **8.5mm.**

Typical Performance





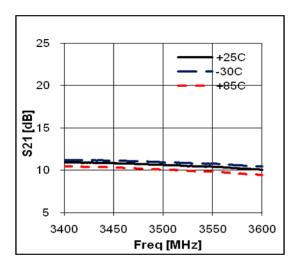
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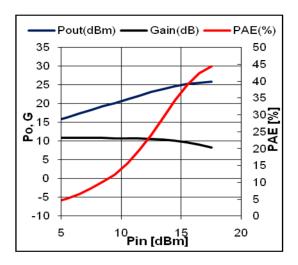
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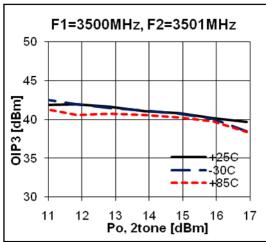
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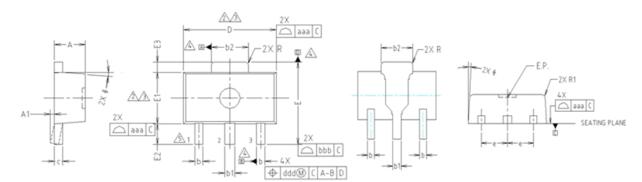








Package Outline Dimension



NOTE:

1. DIMENSIONS IN MILLIMETERS.

DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 8.5mm PER END.

DIMENSION E1 DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION.

INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 8.5mm PER SIDE.

DIMENSIONS D AND E1 ARE DETERMINED AT THE OUTMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.

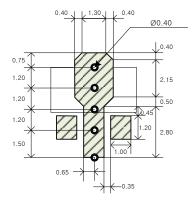
A DATUMS A, B AND D TO BE DETERMINED 8.18mm FROM THE LEAD TIP.

TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.

		NOTE			
SYMBOL	MINIMUM	NOMINAL		MAXIMUM	NOIE
A	1.40	1	.50	1.60	
A1	0.00		_	0.10	
ь	0.38	0).42	0.48	
ь1	0.48	0	.52	0.58	
b2	1.79	1	.82	1.87	
C	0.40	0	.42	0.46	
D	4.40	4	.50	4.70	2,3
E	3.70	4.00		4.30	
E E1	2.40	2.50		2.70	2,3
E2	0.80	1	.00	1.20	
E3	0.40	0.50		0.60	
e	1,50 TYP.				
0	4° TYP.				
R	0.15 TYP.				
R1	-		_	0.20	
SYMBOL	TOLERANCES OF AND POSI	FORM	NOTE		
aaa	0.15]	
bbb	0.20]	
ccc	0.10				
ddd	0.10				

Suggested PCB Land Pattern and PAD Layout

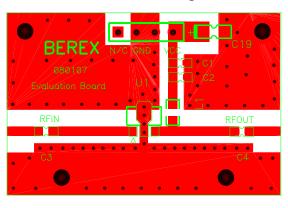
PCB Land Pattern



Note: All dimension are in millimeters

PCB lay out _ on BeRex website

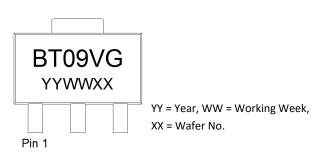
PCB Mounting





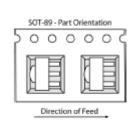


Package Marking



Tape & Reel

SOT89



Packaging information:

Tape Width (mm): 12
Reel Size (inches): 7
Device Cavity Pitch (mm): 8

Devices Per Reel: 1000

Lead plating finish

100% Tin Matte finish

(All BeRex products undergoes a 1 hour, 150 degree C, Anneal bake to eliminate thin whisker growth concerns.)

MSL / ESD Rating

ESD Rating: Class 1B

Value: Passes <1000V

Test: Human Body Model (HBM)

Standard: JEDEC Standard JESD22-A114B

MSL Rating: Level 1 at +265°C convection reflow

Standard: JEDEC Standard J-STD-020



Proper ESD procedures should be followed when handling this device.

NATO CAGE code:

2 N 9	6 F
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